



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Makoto TERUI et al.

Group Art Unit: 2823

Serial No: 10/717,934

Examiner: Brewster, William M

Filed: November 21, 2003

For: METHOD FOR FABRICATING A SEMICONDUCTOR DEVICE HAVING A  
HEAT SPREADING LAYER

**RESPONSE TO ELECTION/RESTRICTION REQUIREMENT**

U.S. Patent and Trademark Office  
Customer Service Window  
Randolph Building  
401 Dulany Street  
Alexandria VA 22314

Sir:

In response to the Office Action of December 29, 2004, Applicants elect Species 1,  
claims 1-3, 6: forming a heat spreading material on the second surface of the semiconductor  
wafer and then after the spreading, separating the die. Claims 1 and 6 are generic.

Respectfully submitted,

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